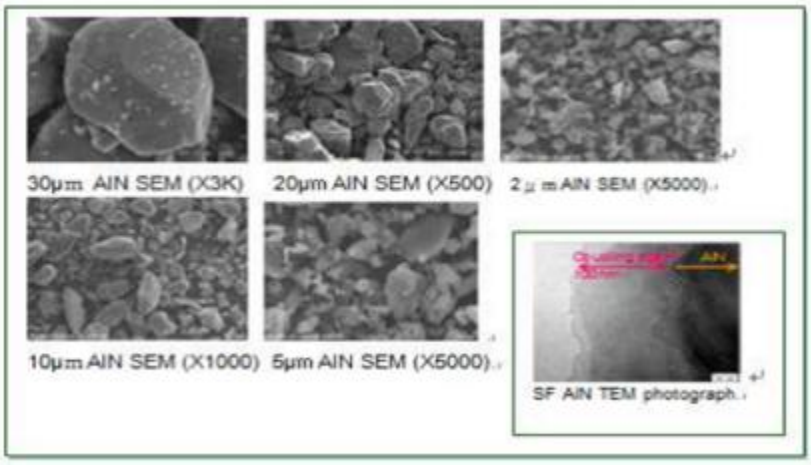
ALN-Aluminum Nitride Powder

High thermal conductivity for Ceramics Substrate application and filer into various of resin can be improved by ALN powder



1. Thrutek AlN-SF series: surface treatment process

Aluminum Nitride (AlN) Powder has been increasingly used as substrate materials for electronic packaging and as fillers to improve the thermal conductivity of polymer composites due to its excellent thermal conductivity and the electrical insulation properties. Thrutek AlN-SF series AlN powder with surface modification enhanced coupling effect with organic matrix. A protection layer is formed on the surface of AlN powder to avoid hydrolysis. Thrutek AlN powder is used as fillers in compound material and ceramic substrate applications.

Application: Thermal Interface Material (TIM)

- Thermal Conductive Additives/Filler
- Epoxy Molding Compound (EMC) TIM additives
- FCCL, MCPCB Dielectric layer as TIM thermal Filler
- TIM thermal filler (Thermal grease, tape, adhesive, rubber)

2. Thrutek AlN-AF series: low iron impurity less than 200ppm

Aluminum Nitride (AlN) Powder has been increasingly used as substrate materials for electronic packaging and as fillers to improve the thermal conductivity of polymer composites due to its excellent thermal conductivity and the electrical insulation properties. Thrutek AlN-AF series AlN powder Fe impurity is below 200ppm. Thrutek AlN powder is used as fillers in compound material and ceramic substrate applications.

Application: Thermal Interface Material (TIM)

- Thermal Conductive Additives/Filler
- TIM thermal filler for EMC Additives, FCCL, MCPCB Dielectric layer.
- TIM thermal filler (Thermal grease, tape, adhesive, rubber)
- High thermal conductivity with low Iron impurity.

3. Thrutek AlN-BF series: low iron impurity less than 700ppm

Aluminum Nitride (AlN) Powder has been increasingly used as substrate materials for electronic packaging and as fillers to improve the thermal conductivity of polymer composites due to its excellent thermal conductivity and the electrical insulation properties. Thrutek AlN-BF series AlN powder Fe impurity is below 700ppm. Thrutek AlN powder is used as fillers in compound material and ceramic substrate applications.

Application: Thermal Interface Material (TIM)

- Thermal Conductive Additives/Filler
- TIM thermal filler for EMC Additives, FCCL, MCPCB Dielectric layer.
- TIM thermal filler (Thermal grease, tape, adhesive, rubber)
- TIM thermal filler (Thermal ink, painting)

4. Thrutek AlN-SS series: low iron impurity less than 200ppm

Aluminum Nitride (AlN) Powder has been increasingly used as substrate material for electronic packaging of semiconductor to improve the thermal conductivity and heat dissipation due to its excellent thermal conductivity, electrical insulation and lower thermal expansion properties. Thrutek SS series are supplied for sintering application of Aluminum Nitride ceramics with standard and customized particle size (D50) for different sintering condition. The ceramic density may reach 3.28~3.33g/cm3 at 1775~1825℃ sintering for 2 hours in inert atmosphere as typical sintering aid 3~6% Y2O3 is added.

Application: Sintering Ceramics Substrate Use

- High Thermal Conductive Ceramics Substrate.
- Semiconductor high thermal conductive parts, others advanced and functional ceramics parts.
- LED substrate for high heat dissipation.
- High thermal conductivity with low Iron impurity.

Characteristic

Ceramic material widely used in Semiconductor industry, Electronics industry, Electrical industry with fully function of High thermal conductivity, High electrical resistance, High hardness, Corrosion resistant, Low dielectric loss and Low CTE.

Product Features

- Sharp size distribution
- Good dispersion
- Low metal impurities
- Low oxygen contents
- Low CTE (Coefficient of Thermal Expansion)
- Continuous volume production, monthly up to eight tonnage capacity

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